

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	US-5686353-\$.DID. OR US-20030148593-\$.DID. OR US-20040169020-\$.DID. OR JP-2000138255-\$.DID. OR JP-2000138255051600-\$.DID. OR JP-63101085-\$.DID. OR JP-63101085050688-\$.DID. OR JP-2001351892-\$.DID. OR JP-2001351892122101-\$.DID. OR JP-57195593-\$.DID. OR JP-57195593120182-\$.DID. OR JP-8181144-\$.DID. OR JP-8181144071296-\$.DID. OR JP-2791429-\$.DID. OR JP-2791429082798-\$.DID. OR JP-1092702-\$.DID.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/11/24 10:58
S2	146	suga-tadatomo.in. or okada-masuaki.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:14
S3	5	S2 and bond\$3 same (gold or Au or copper or Cu) same solid\$3 same (chip or wafer or substrate) and ((energy near\$5 treat\$4) or beam or atom\$3 or ion or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:26
S4	112	KIMURA-TAKEHIRO.in. or ISOZAKI-SEIYA.in. or HASHIMOTO-KATSUMASA.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:29
S5	4	S4 and bump\$3 same (gold or Au) same bond\$3 and (chip or wafer or substrate) and (beam or plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 11:30
S6	10	("5604379"   "5672912"   "5874784"   "5892271"   "5953592"   "6140707"   "6232650").PN. OR ("6400034").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:34
S7	2158	228/116,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:45
S8	0	438/455.ccls	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:46
S9	1803	438/455.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:47

S10	6	(S7 or S9) and (solid near5 (state or phase) same bond\$3 same (room or ambient or low) near5 temperature and (gold or Au) same (chip or wafer or substrate) and (beam or plasma))	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 11:49
S11	0	EP-711097-4.did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 14:25
S12	2	EP-711097-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 14:25
S13	8	("5407864"   "5912507").PN. OR ("6288445").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/24 16:31
S14	89204	toray.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:49
S15	0	S14 and tadatomo-suga.in. and bond\$3 same room same temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:50
S16	397	S14 and bond\$3 same room same temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:50
S17	395	S14 and bond\$3 same room near5 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:50
S18	4	S14 and bond\$3 same room near5 temperature and energy same wave same clean\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:51
S19	0	wo-2002054476-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:54

S20	0	wo-200254476-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:55
S21	0	wo-0254476-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 16:55
S22	4	"2004047127"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:00
S23	2	"20040047127"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:00
S24	3	"20060016555"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:11
S25	89207	toray.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S26	395	S25 and bond\$3 same room near5 temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S27	0	S26 and (copper or cu) near10 (pad or pads or electrode or electrodes or land or lands) same diffus\$4 same (au or gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S28	2160	228/116,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 14:00
S29	1806	438/455.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 14:00

S30	29	(S28 or S29) and (copper or cu) near10 (pad or pads or electrode or electrodes or land or lands) same diffus\$4 same (au or gold)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:00
S31	2	("5833758").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/25 15:46
S32	0	RF near10 plasma same clean\$3 same rough\$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:55
S33	1	plasma same clean\$3 same rough \$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:55
S34	1	RF same plasma same clean\$3 and rough\$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:55
S35	7	plasma same clean\$3 and rough \$4 near10 Ry	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:57
S36	540	plasma same clean\$3 and rough \$4 near10 Ra	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:06
S37	40	RF same plasma same clean\$3 and rough\$4 near10 Ra	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:06
S38	23	S37 and @ad<"20040201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:06

S39	76	semiconductor same bond\$3 and plasma same clean\$3 and rough \$4 near10 Ra	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:16
S40	9099711	"10" and @ad<"20040201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:17
S41	39	S39 and @ad<"20040122"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 16:17
S42	2	("5686353").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/25 17:25

11/26/2008 9:34:48 AM

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